



REMARKS

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Claims 1-34 are pending in the present Application.

The Specification has been amended after the title to add a cross-reference to related application. The Specification has also been amended at page 2 to correct a typographical error.

Claims 1, 7, 14, 23, 27 and 33 have been amended to correct typographical errors. Support can be found in the Specification at page 4, lines 2-4. Claims 5, 12, 22 and 31 have been amended to define the conductive polymers differently. Support is found in the Specification at page 5, lines 10-16. Claims 6, 13, 22 and 32 have been amended to change their dependencies. Claims 8 and 17 have been amended to make clear that the first step is the deposition of a seed layer. None of the claims are being amended to overcome any prior art rejection.

No new matter is added with this Amendment.

Claims 1-34 are subject to a restriction requirement as follows:

Group I – claims 1-7 and 27-33,

Group II – claims 8-26; and

Group III – claim 34.

Applicants elect Group I, with traverse.

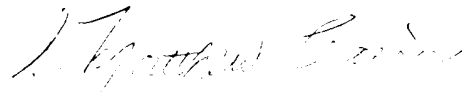
Groups I and II are related. Group I is directed to an electroless method of depositing a conductive seed layer. Group II is directed to a 2-step process, the first step of which is *electrolessly depositing a conductive seed layer*. This electroless conductive seed layer deposition methods of Groups I and II are commensurate in scope. They have the same mode of operation (electroless deposition), they have the same function (to deposit a conductive layer on a non-conductive surface) and they have the same effect (to provide a conductive surface for subsequent metal electroplating).

Based on the foregoing, it is submitted that the search and examination of the entire application could be made without serious burden. See MPEP §803 which states that "If the search and examination of an entire application can be made without serious burden, the

Examiner must examine it on the merits, even though it includes claims to distinct or independent inventions." It is respectfully submitted that this policy should apply in the present application in order to avoid unnecessary delay and expense to Applicants and duplicative examination by the Patent Office. Accordingly, Applicants respectfully request rejoinder of Groups I, II and III.

Applicants respectfully request favorable consideration in the form of a notice of allowance.

Respectfully submitted,



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